PD - 95637A

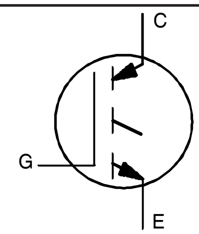
International
IOR Rectifier

IRG4IBC30SPbF

INSULATED GATE BIPOLAR TRANSISTOR

Features

- Standard: Optimized for minimum saturation voltage and low operating freqencies (<1 kHz)
- Generation 4 IGBT design provides tighter parameter distribution and higher efficiency than previous generation
- Industry standard TO-220 Full-Pak
- Lead-Free



N-channel

V_{CES} = 600V

$V_{CE(on)\ typ.}$ = 1.4V

@V_{GE} = 15V, I_C = 18A

Benefits

- Generation 4 IGBTs offer highest efficiencies available
- IGBTs optimized for specific application conditions
- Designed to be a "drop-in" replacement for equivalent industry -standard Generation 3 IR IGBTs

TO-220 Full-Pak

Absolute Maximum Ratings

	Parameter	Max.	Units
V_{CES}	Collector-to-Emitter Breakdown Voltage	600	V
I_C @ T_C = 25°C	Continuous Collector Current	23.5	A
I_C @ T_C = 100°C	Continuous Collector Current	13.0	
I_{CM}	Pulsed Collector Current ①	47	
I_{LM}	Clamped Inductive Load Current ②	47	
V_{GE}	Gate-to-Emitter Voltage	± 20	V
E_{ARV}	Reverse Voltage Avalanche Energy ③	10	mJ
P_D @ T_C = 25°C	Maximum Power Dissipation	45	W
P_D @ T_C = 100°C	Maximum Power Dissipation	18	
T_J T_{STG}	Operating Junction and Storage Temperature Range	-55 to + 150	°C
	Soldering Temperature, for 10 seconds	300 (0.063 in. (1.6mm) from case)	

Thermal Resistance

	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	——	2.8	°C/W
$R_{\theta JA}$	Junction-to-Ambient, typical socket mount	——	65	
Wt	Weight	2.1 (0.075)	——	g (oz)

06/17/2010

Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions	
$V_{(BR)CES}$	Collector-to-Emitter Breakdown Voltage	600	—	—	V	V_{GE} = 0V, I_C = 250µA	
$V_{(BR)ECS}$	Emitter-to-Collector Breakdown Voltage ④	18	—	—	V	V_{GE} = 0V, I_C = 1.0A	
$\Delta V_{(BR)CES}/\Delta T_J$	Temperature Coeff. of Breakdown Voltage	—	0.75	—	V/°C	V_{GE} = 0V, I_C = 1.0mA	
$V_{CE(ON)}$	Collector-to-Emitter Saturation Voltage	—	1.40	1.6	V	I_C = 18A	V_{GE} = 15V
		—	1.84	—		I_C = 34A	See Fig.2, 5
		—	1.45	—		I_C = 18A , T_J = 150°C	
$V_{GE(th)}$	Gate Threshold Voltage	3.0	—	6.0		$V_{CE} = V_{GE}$, I_C = 250µA	
$\Delta V_{GE(th)}/\Delta T_J$	Temperature Coeff. of Threshold Voltage	—	-11	—	mV/°C	$V_{CE} = V_{GE}$, I_C = 250µA	
g_{fe}	Forward Transconductance ⑤	6.0	11	—	S	V_{CE} = 100 V, I_C = 18A	
I_{CES}	Zero Gate Voltage Collector Current	—	—	250	µA	V_{GE} = 0V, V_{CE} = 600V	
		—	—	2.0		V_{GE} = 0V, V_{CE} = 10V, T_J = 25°C	
		—	—	1000		V_{GE} = 0V, V_{CE} = 600V, T_J = 150°C	
I_{GES}	Gate-to-Emitter Leakage Current	—	—	±100	nA	V_{GE} = ±20V	

Switching Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
Q_g	Total Gate Charge (turn-on)	—	50	75	nC	I_C = 18A
Q_{ge}	Gate - Emitter Charge (turn-on)	—	7.3	11		V_{CC} = 400V See Fig.8
Q_{gc}	Gate - Collector Charge (turn-on)	—	17	26		V_{GE} = 15V
$t_{d(on)}$	Turn-On Delay Time	—	22	—	ns	
t_r	Rise Time	—	18	—		T_J = 25°C
$t_{d(off)}$	Turn-Off Delay Time	—	540	810		I_C = 18A, V_{CC} = 480V
t_f	Fall Time	—	390	590		V_{GE} = 15V, R_G = 23Ω
E_{on}	Turn-On Switching Loss	—	0.26	—	mJ	Energy losses include "tail"
E_{off}	Turn-Off Switching Loss	—	3.45	—		See Fig. 9, 10, 14
E_{ts}	Total Switching Loss	—	3.71	5.6		
$t_{d(on)}$	Turn-On Delay Time	—	21	—	ns	T_J = 150°C,
t_r	Rise Time	—	19	—		I_C = 18A, V_{CC} = 480V
$t_{d(off)}$	Turn-Off Delay Time	—	790	—		V_{GE} = 15V, R_G = 23Ω
t_f	Fall Time	—	760	—		Energy losses include "tail"
E_{ts}	Total Switching Loss	—	6.55	—	mJ	See Fig. 10, 11, 14
L_E	Internal Emitter Inductance	—	7.5	—	nH	Measured 5mm from package
C_{ies}	Input Capacitance	—	1100	—	pF	V_{GE} = 0V
C_{oes}	Output Capacitance	—	72	—		V_{CC} = 30V See Fig. 7
C_{res}	Reverse Transfer Capacitance	—	19	—		f = 1.0MHz

Notes:

① Repetitive rating; V_{GE} = 20V, pulse width limited by max. junction temperature. (See Fig. 13b)

② V_{CC} = 80%(V_{CES}), V_{GE} = 20V, L = 10µH, R_G = 23Ω, (See Fig. 13a)

③ Repetitive rating; pulse width limited by maximum junction temperature.

④ Pulse width ≤ 80µs; duty factor ≤ 0.1%.

⑤ Pulse width 5.0µs, single shot.

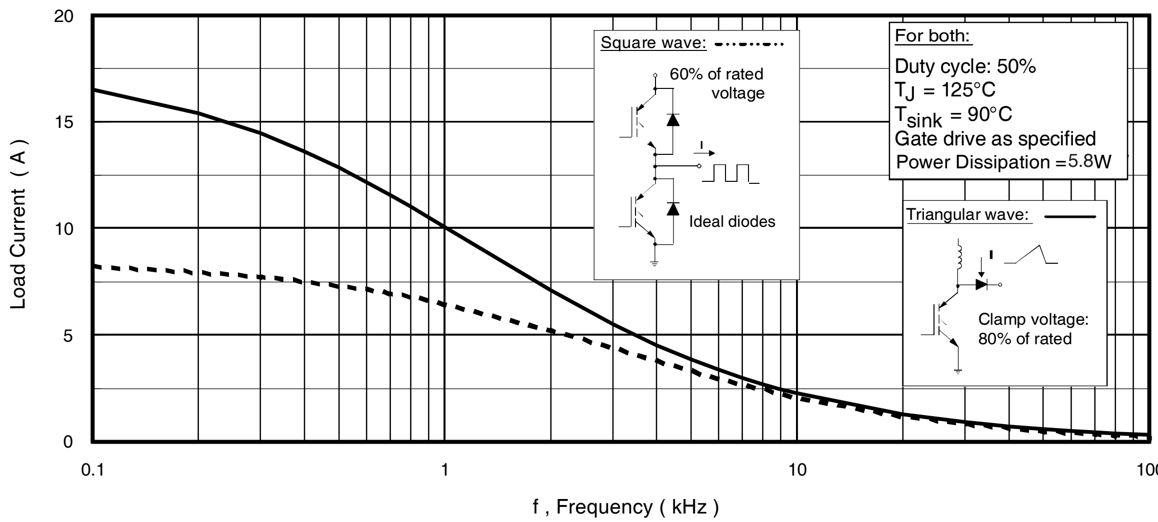


Fig. 1 - Typical Load Current vs. Frequency
(Load Current = I_{RMS} of fundamental)

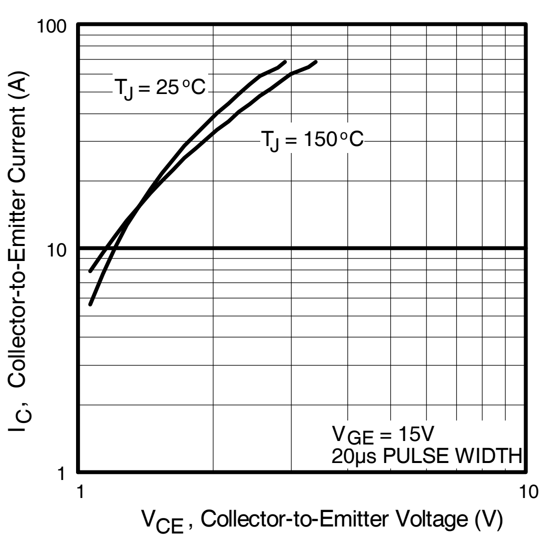


Fig. 2 - Typical Output Characteristics

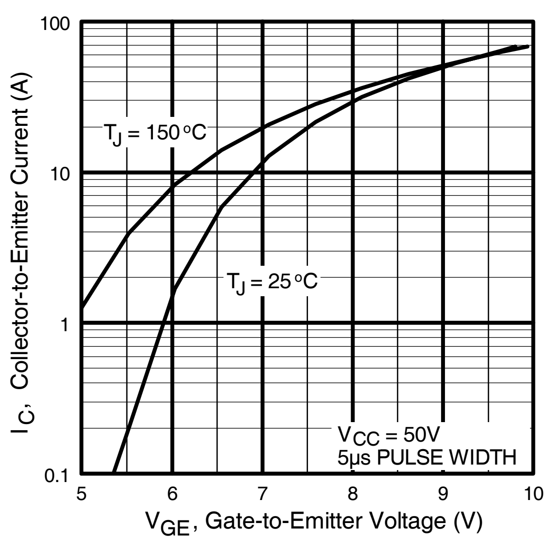


Fig. 3 - Typical Transfer Characteristics

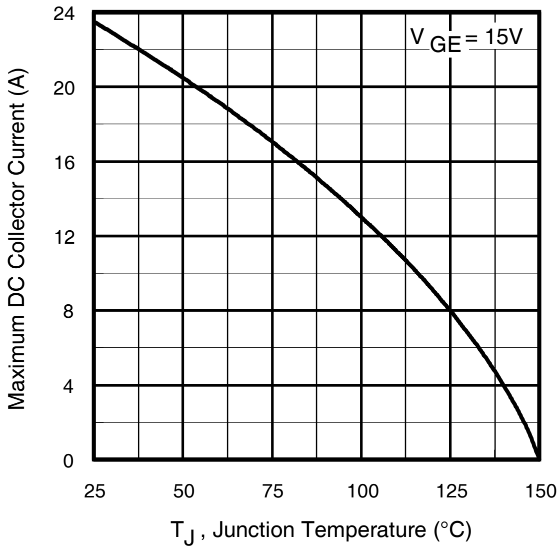


Fig. 4 - Maximum Collector Current vs. Case Temperature

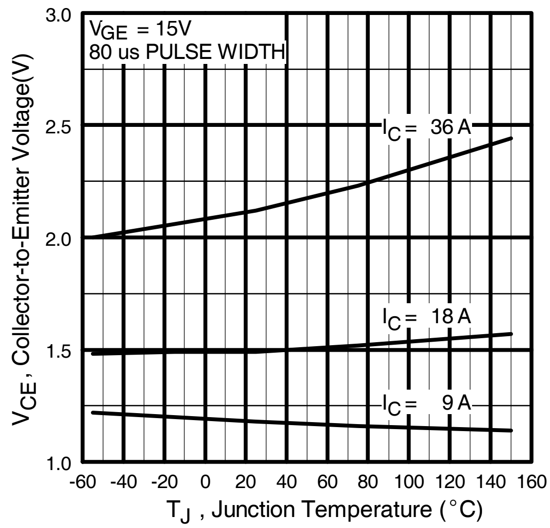


Fig. 5 - Typical Collector-to-Emitter Voltage vs. Junction Temperature

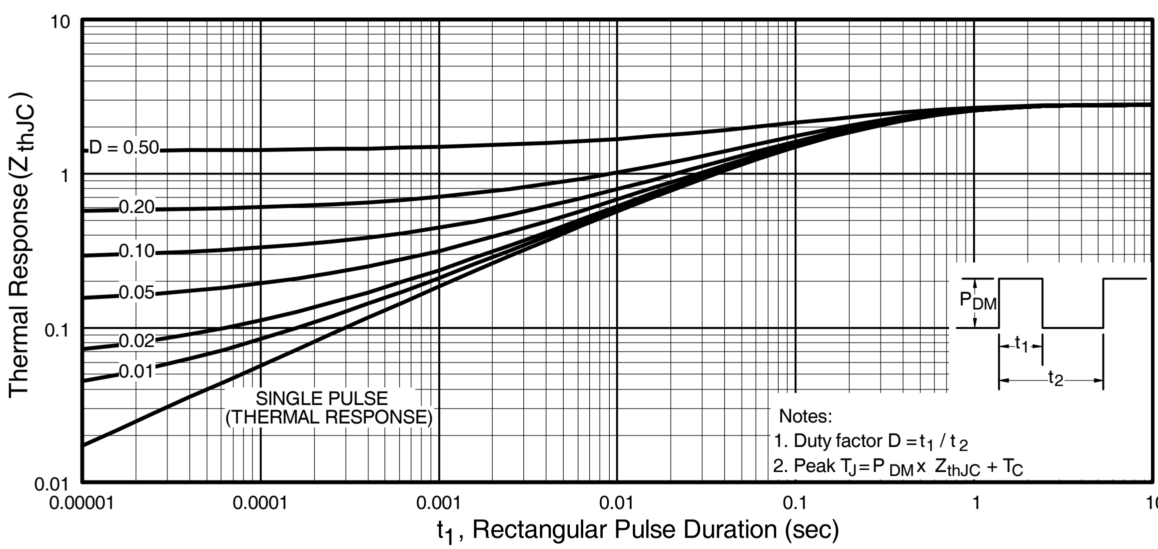


Fig. 6 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

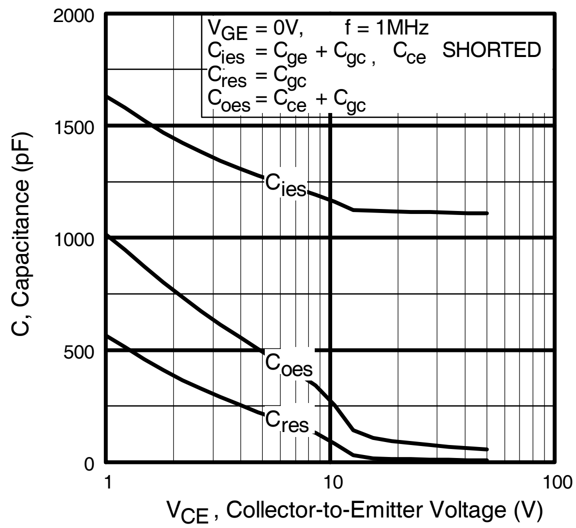


Fig. 7 - Typical Capacitance vs. Collector-to-Emitter Voltage

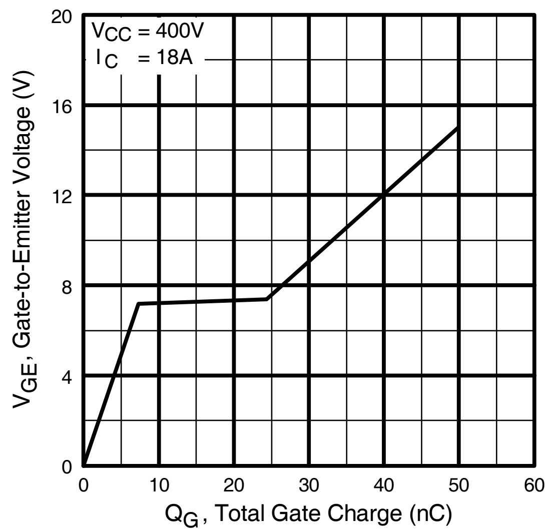
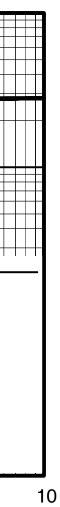


Fig. 8 - Typical Gate Charge vs. Gate-to-Emitter Voltage



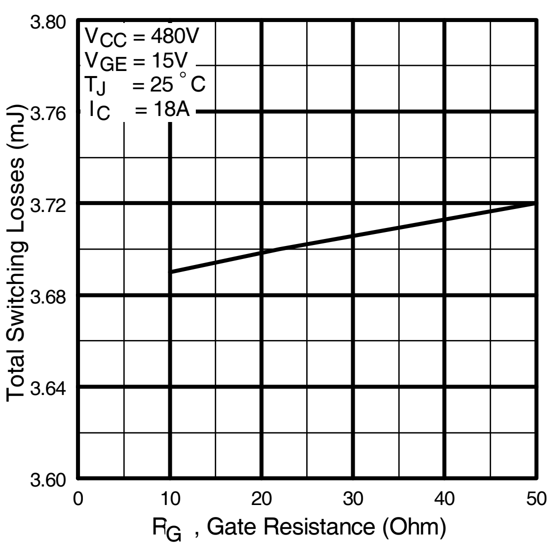


Fig. 9 - Typical Switching Losses vs. Gate Resistance

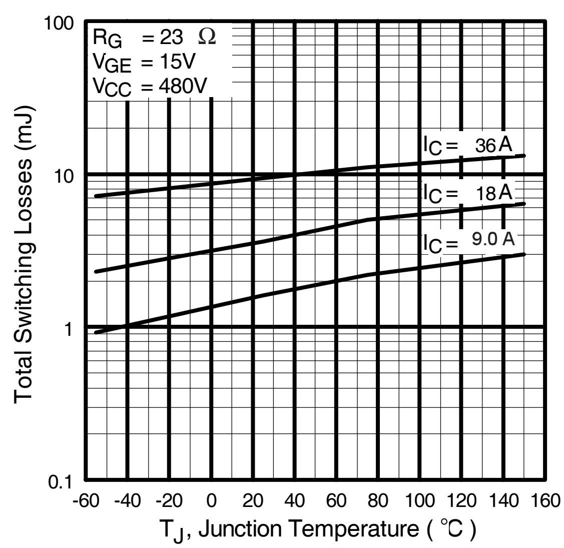


Fig. 10 - Typical Switching Losses vs. Junction Temperature

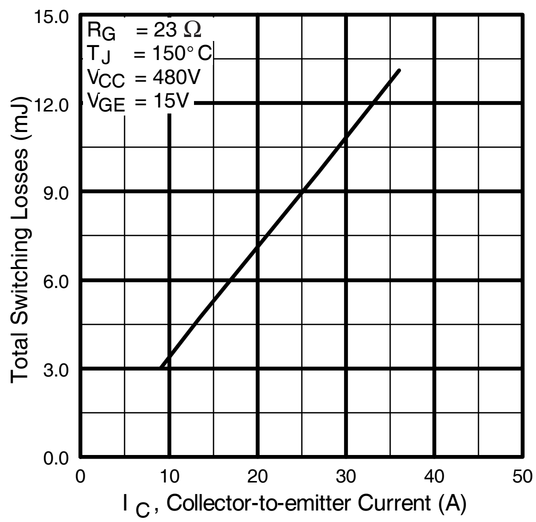


Fig. 11 - Typical Switching Losses vs. Collector-to-Emitter Current

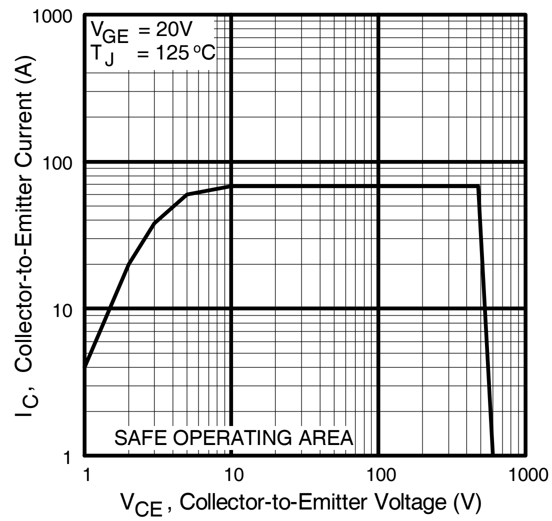


Fig. 12 - Turn-Off SOA

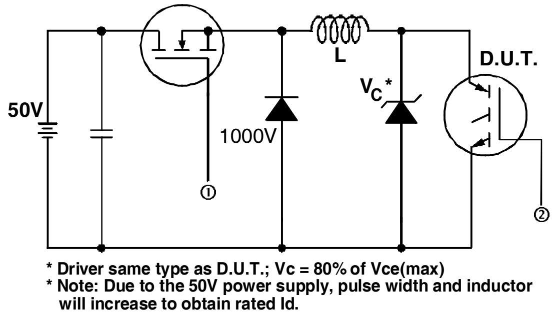


Fig. 13a - Clamped Inductive Load Test Circuit

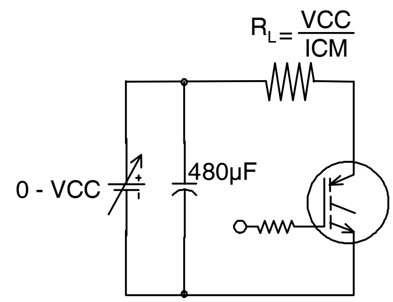


Fig. 13b - Pulsed Collector Current Test Circuit

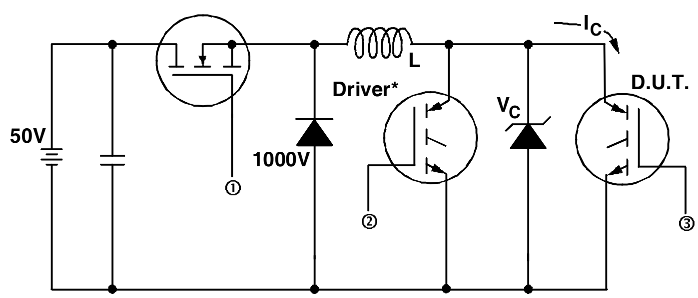


Fig. 14a - Switching Loss Test Circuit

* Driver same type as D.U.T., VC = 480V

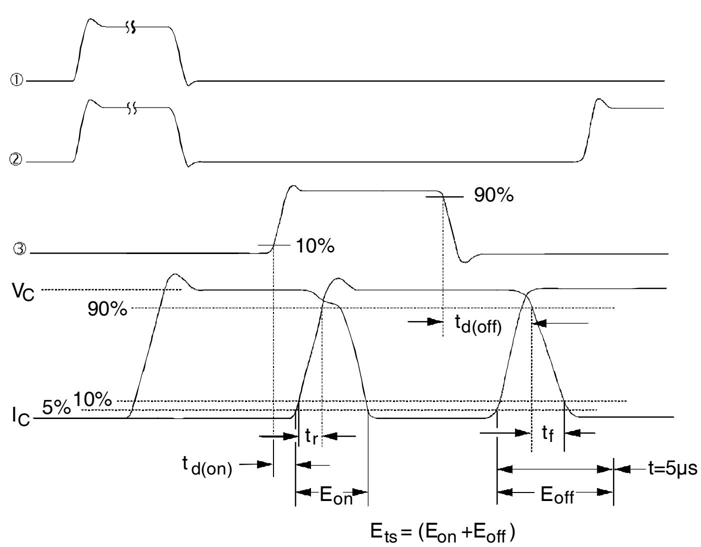
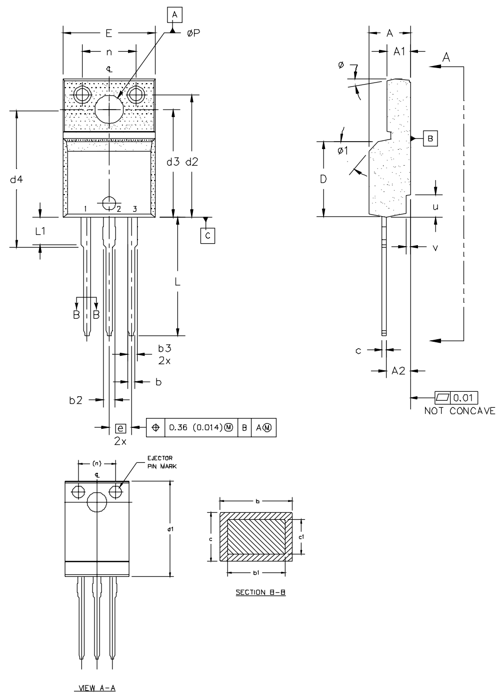


Fig. 14b - Switching Loss Waveforms

TO-220 Full-Pak Package Outline

Dimensions are shown in millimeters (inches)



NOTES:

1.0 DIMENSIONING AND TOLERANCING PER ASME Y14.5 M- 1994.
2.0 DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES]
3.0 LEAD DIMENSION AND FINISH UNCONTROLLED IN L1.
4.0 DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.005" (0.127) PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
5.0 DIMENSION b1 APPLY TO BASE METAL ONLY.
6.0 STEP OPTIONAL ON PLASTIC BODY DEFINED BY DIMENSIONS u & v.
7.0 CONTROLLING DIMENSION : INCHES.

SYMBOL	DIMENSIONS				NOTES
	MILLIMETERS		INCHES		
	MIN.	MAX.	MIN.	MAX.	
A	4.57	4.83	0.180	0.190	
A1	2.57	2.83	0.101	0.114	
A2	2.51	2.85	0.099	0.112	
b	0.622	0.89	0.024	0.035	
b1	0.622	0.838	0.024	0.033	5
b2	1.229	1.400	0.048	0.055	
b3	1.229	1.400	0.048	0.055	
c	0.440	0.629	0.017	0.025	
c1	0.440	0.584	0.017	0.023	
D	8.65	9.80	0.341	0.386	4
d1	15.80	16.12	0.622	0.635	
d2	13.97	14.22	0.550	0.560	
d3	12.30	12.92	0.484	0.509	
d4	8.64	9.91	0.340	0.390	
E	10.36	10.63	0.408	0.419	4
e	2.54 BSC		0.100 BSC		
L	13.20	13.73	0.520	0.541	
L1	3.10	3.50	0.122	0.138	3
n	6.05	6.15	0.238	0.242	
øP	3.05	3.45	0.120	0.136	
u	2.40	2.50	0.094	0.098	6
v	0.40	0.50	0.016	0.020	6
ø	3°	7°	3°	7°	
ø1		45°		45°	

LEAD ASSIGNMENTS

HEXFET

1.- GATE
2.- DRAIN
3.- SOURCE

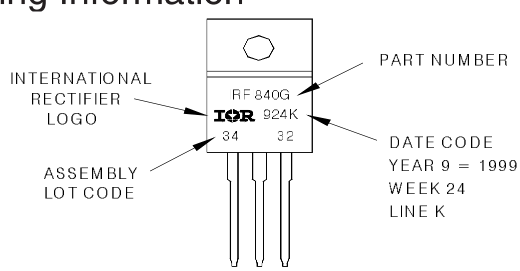
IGBTs, CoPACK

1.- GATE
2.- COLLECTOR
3.- EMITTER

TO-220 Full-Pak Part Marking Information

EXAMPLE: THIS IS AN IRFI840G
WITH ASSEMBLY
LOT CODE 3432
ASSEMBLED ON WW 24 1999
IN THE ASSEMBLY LINE "K"

Note: "P" in assembly line position indicates "Lead-Free"



Note: For the most current drawing please refer to IR website at http://www.irf.com/package/

Data and specifications subject to change without notice.
This product has been designed and qualified for the Industrial market.
Qualification Standards can be found on IR's Web site.

International
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